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moving the light output along a path of the frit layer at a predetermined rate to carbonize the frit layer to effect release of the windscreen panel from the frame.

47. (NEW) A method of releasing a windscreen panel from a frame to which the windscreen panel is bonded by interposed bonding material, the method comprising the steps of:

directing light output from an array of laser diodes at a frit layer on an inside face of the windscreen panel about a periphery thereof and conforming to the frame;

providing the light output at a wavelength absorbed by the frit layer; and

moving the light output along a path of the frit layer at a predetermined rate to carbonize the frit layer to effect release of the windscreen panel from the frame.

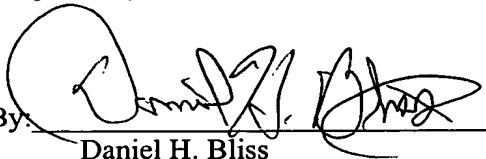
REMARKS

New claims 46 and 47 have been added. Claims 1 through 47 remain in the application.

Attached to this Preliminary Amendment is a new Declaration and Power of Attorney claiming the benefit of 35 U.S.C. § 120 of prior U.S. patent application Serial No. 09/133,854 and 08/693,060. Applicants have amended the Specification to contain a specific reference to Serial No. 09/133,854, which is still pending and Serial No. 08/693,060.

Applicants have added new claims 46 and 47 to claim additional subject matter to which Applicants are entitled. Applicants look forward to early consideration of the pending claims.

Respectfully submitted,

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